

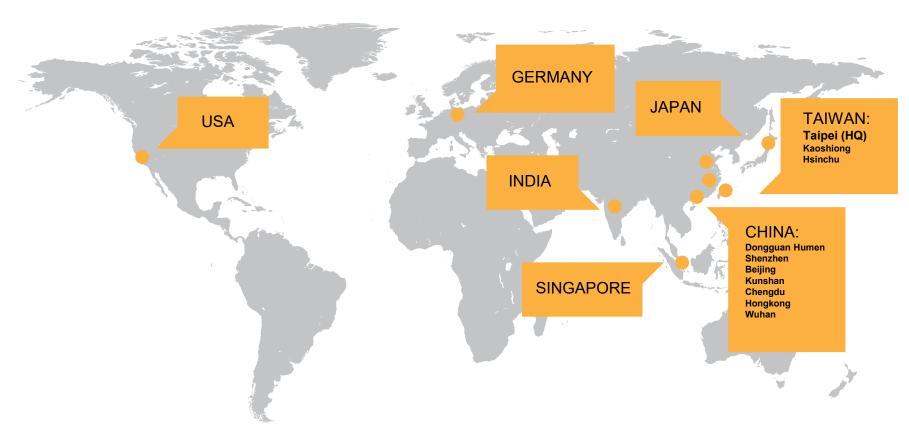
## **Company Introduction**

CCP Contact Probes Co., Ltd.

## **History**

- 2019 Germany Japan Singapore Office established.
- 2018 India Office established.
- 2016 Industrial Connector & Crown Spring Connector.
- 2014 CCP US Office established.
- 2012 Set up 100k class clean room production line.
- 2006 IC Testing
- 2003 Listed in Taiwan Stock Market (TW.6217).
- 2002 Pogo Pin Connector
- 2001 Dongguan CCP Contact Probes Co., Ltd established.
  - 1998 Renamed to CCP Contact Probes Co., Ltd.
- 1986 ICT Testing
- 1986 CCP Contact Probes Enterprise Co., Ltd. Established.

## **CCP Group**



#### Selected Customers:











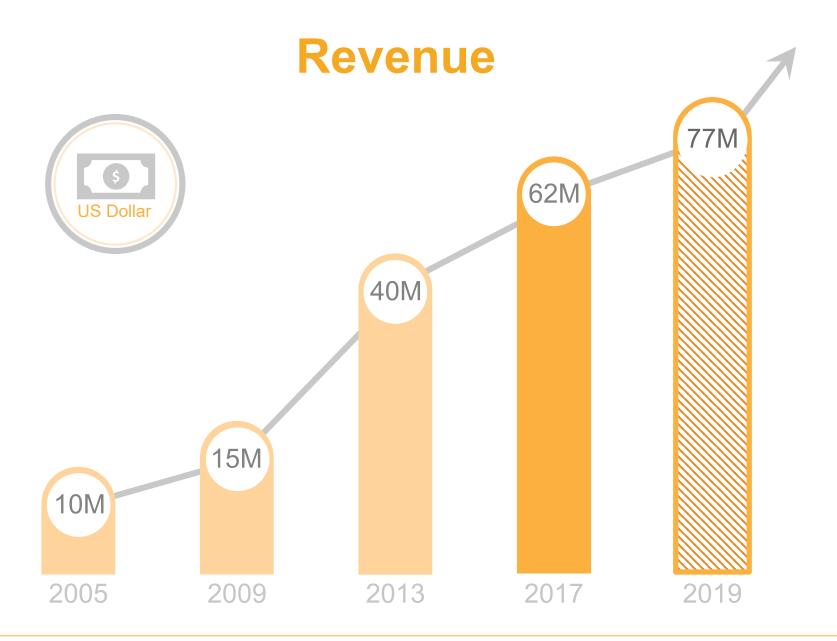












# Staff: R&D Design Service





#### Fundamental Research

IC Testing probe Engineer	9
MEMS Team	7
Plating Lab	6
FAE	3
Automation Engineer	4
IC Socket Design	2



#### **Applied Research**

Pin & Connector R&D	15
Testing Lab	2
FAE	2
Sample Team	8
Fixture Team	1
Coating Lab	2

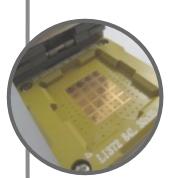
#### Project Management

Project Manager	7
Engineer PM	6

# Plating: Comparison

			G	S	G
Plating	Testing standard	Au(50u") Layer	AP Layer	APII Layer	Super AP Layer
Color	1	Gold	Silver	Silver	Silver
Nickel release	EN 12472:2005+A1 :2009	Nickel-containing process	Nickel-free process	Nickel-free process	Nickel-free process
Plating thickness (micro inch)	XRF	100~170	110-170	270~400	210~400
Impedance (mΩ)	EIA-364-23	< 50	< 50	< 50	< 50
Salt Spray resistance (HR)	EIA-362-26	96	48	96	168
Artificial Sweat resistance (HR)	ISO-3160	96	48	96	168
Surface hardness (HV)	ISO 6507- 1:2005	200	400	400	400
Electrolysis resistance time	1mA,5V,Pitch=0 .60mm	<1min	10min	15min	60min
Cost	Factor to Gold Plating	1	x0.9	x2	<b>x</b> 3

## **Product Portfolio**



**CCP-Testing** 

IC Testing Probe
IC Probe Head
PCB Testing Probe
MEMS Probe



CCP-Connector

Pogo Pin Conn. Waterproof Conn. Magnetic Conn.



CCP-Performance

Electronic Vehicle High Current Conn.



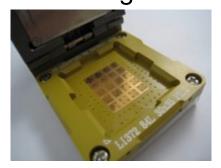
CCP-Industrial Extreme Environment

Aerospace Military Transportation Space

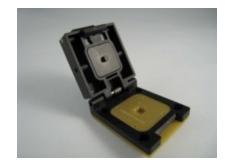
# **Product Line:** Testing



IC Package Test



**Burn-In Test** 



High Current Probe



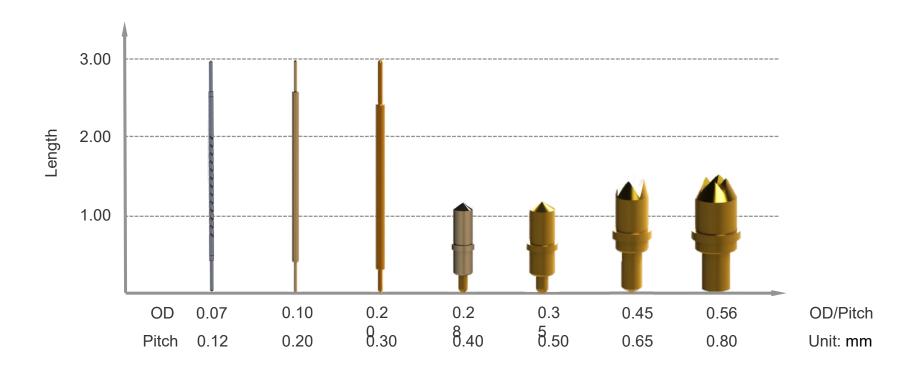
**Memory Test** 



**WLCSP Test** 

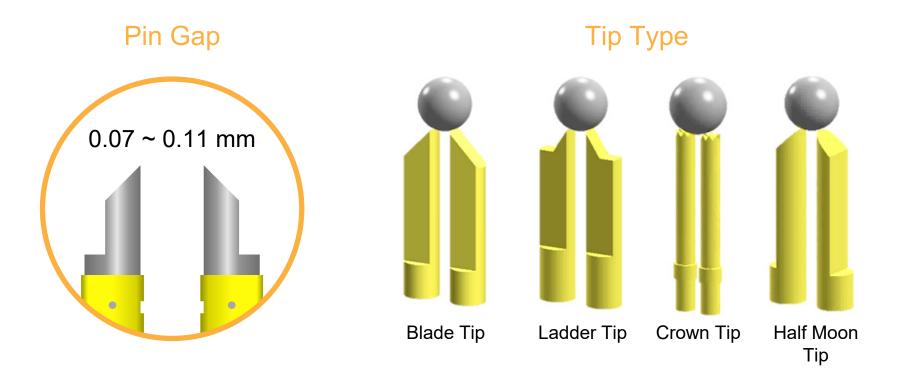


# Testing: Probe Design Capability



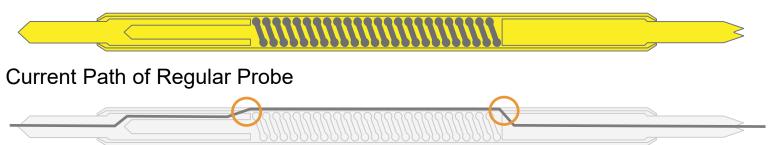
## Testing: Kelvin Bridge Probe

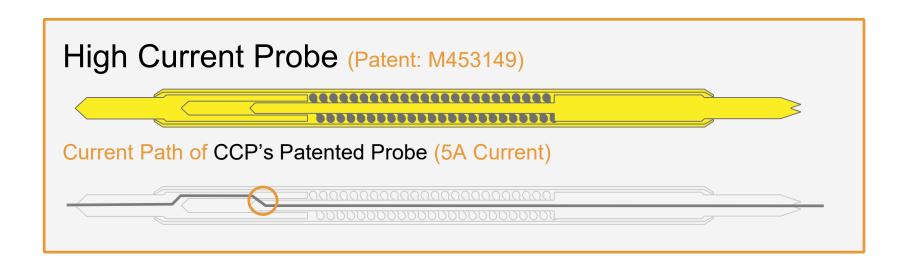
Our testing probe can be in Kelvin bridge style to increase the accuracy of probing.



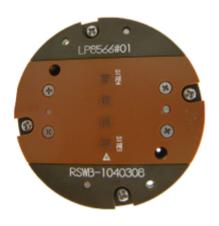
## Testing: High Current Probe

#### Regular Probe

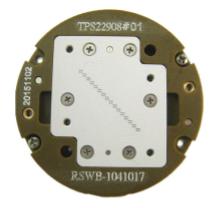




# **Testing: WLCSP**



36 Balls 4 Sites Pitch 0.4mm



4 Balls 16 Sites Pitch 0.5mm



12 Balls 16 Sites Pitch 0.4mm

# Testing: IC Final Test Socket

**BGA** 

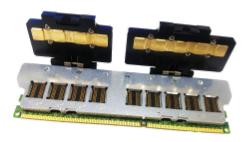


QFN



**Memory Test** 

DDR 1~4 eMCP Flash



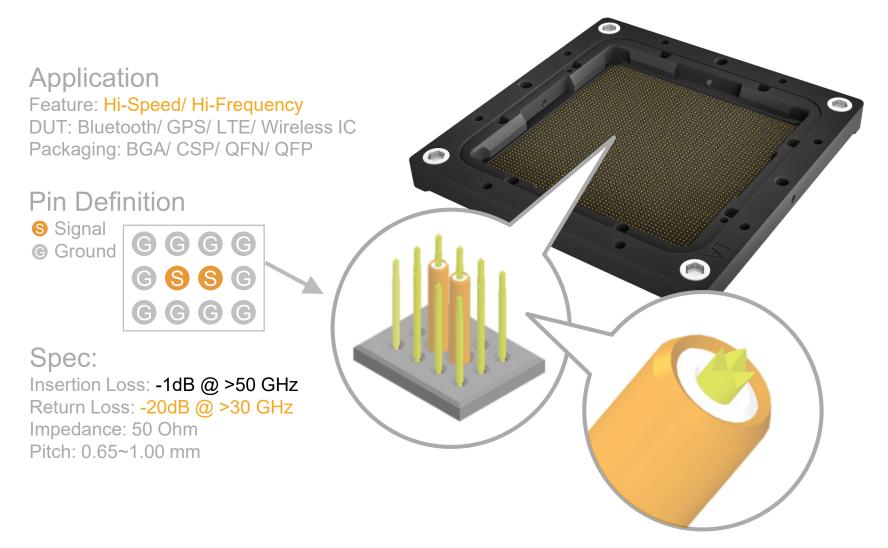
Clamping Lid
QFN QFP
<200 pins



Knob Lid
All Kind
>200 pins



## Testing: Coaxial Socket for RF

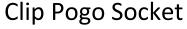


## **Testing:** Testing Socket



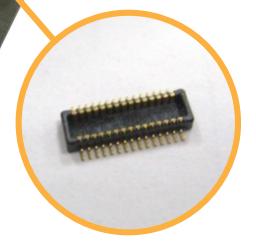
Min Pitch: 0.2

Mechanical Life: 200k

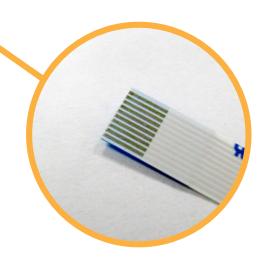


Min Pitch: 0.2

Mechanical Life: 200k



Device Under Test
Fine Pitch Connector



Device Under Test
FPC Gold Finger

## **Testing:** Pogo Tower

A Pogo tower is used to connect load board and mother board inside the tester.



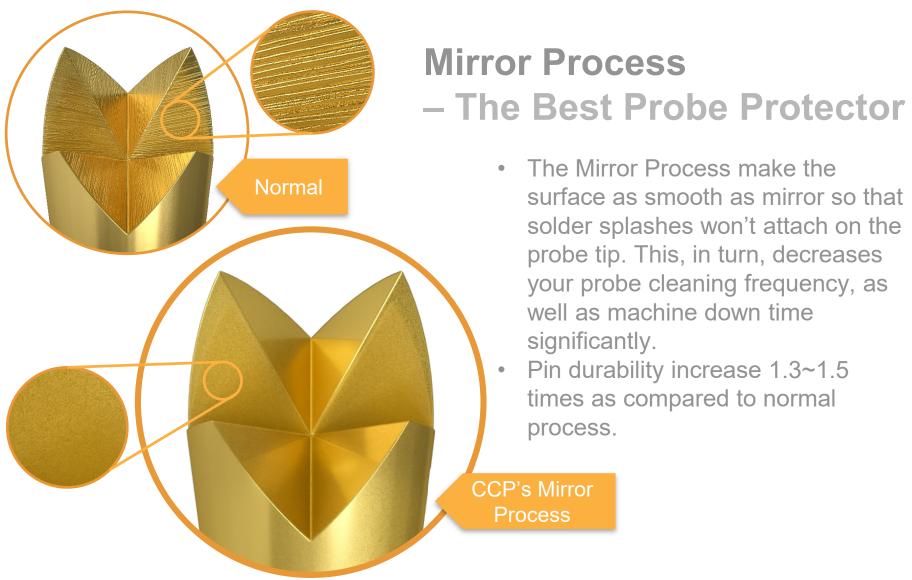
To fit the structure of clients' tester, we customize the design of our pogo tower.





Wired pogo tower provides possibility for flexible connecting structure in testers.

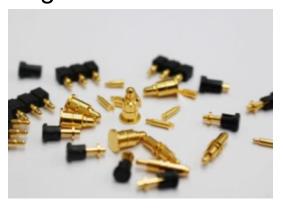
## **Testing:** Mirror Process



## **Product Line:** Connector



Pogo Pin Connector



2 in 1 Tablet Connector



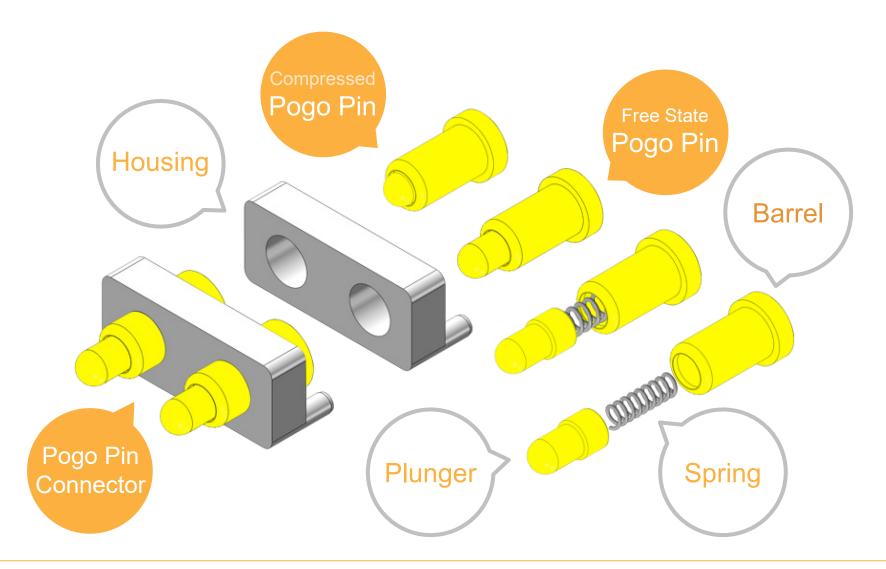
**Magnetic Connector** 



Waterproof Connector



## **Connector:** Basic Structure



## **Connector:** Manufacturing





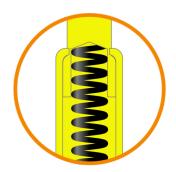
**100% inspection** can be done in automated production line. First ever clean room pogo pin production line in industry.



### **Connector:** Inner Structure

#### **Back Drill**

The drilled tail makes extra space for spring and creates a shorter pogo pin.



Pin Length: ≈ 2.5 mm

Current: 1 A

#### Bias Tail

The bias tail of plunger creates lateral force and better contact.



Pin Length: ≈ 3.5 mm

Current: 2 A

#### Ball

The ball inside stabilizes the contacting areas for a better performance.

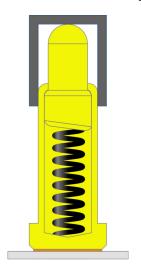


Pin Length: ≈ 4.5 mm

Current: 3~5 A

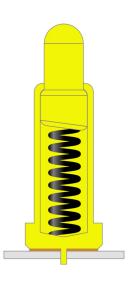
## **Connector:** Installation

#### SMT with Cap



Cap is used for SMT procedure, and it will be removed after being mounted.

Plug-in



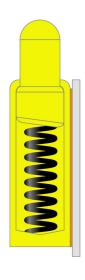
Plug-in tail is used for higher soldering force on PCB when it's needed.

Wired



Wire can be soldered onto a drilled dip for cable module.

#### Right Angle



Side of square tube can be soldering area for different mechanical structure.



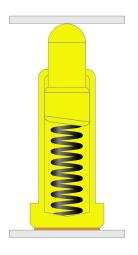


Plastic Cap



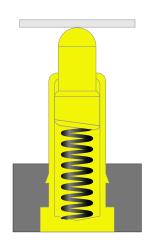
## **Connector:** Installation

#### **Board to Board**



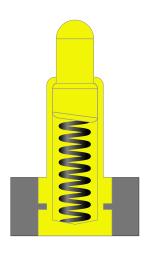
This structure is used to absorb the tolerance inbetween PCBs.

#### Case to Board



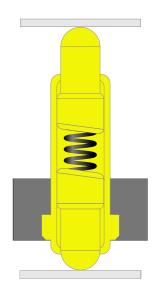
The bottom of pin can also be a cosmetic/contact area if necessary.

#### Insert-molding



Pins can be insertmolded for waterproofing requirement.

#### **Double Ended**



It's possible to have two movable tips.



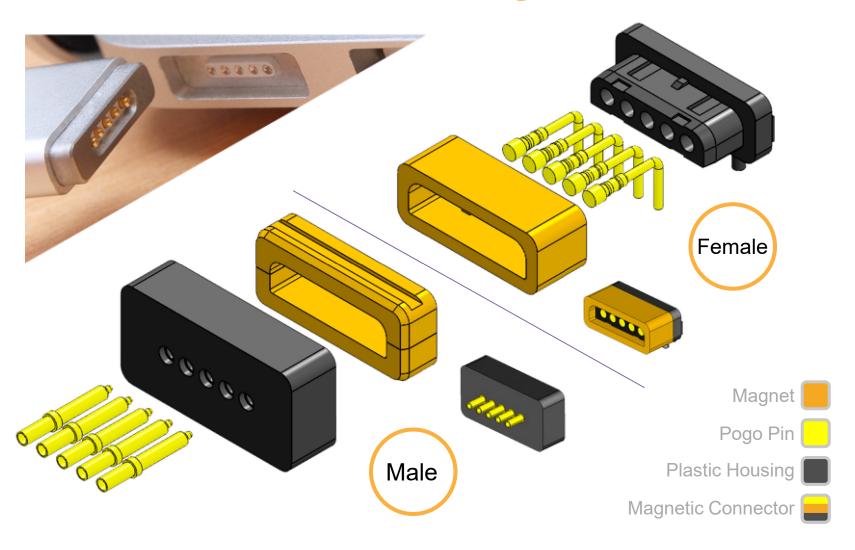


Plastic Housing



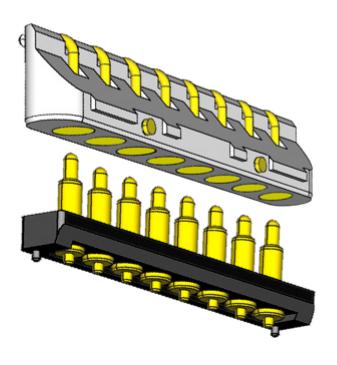
Solder

# **Connector:** Magnetic



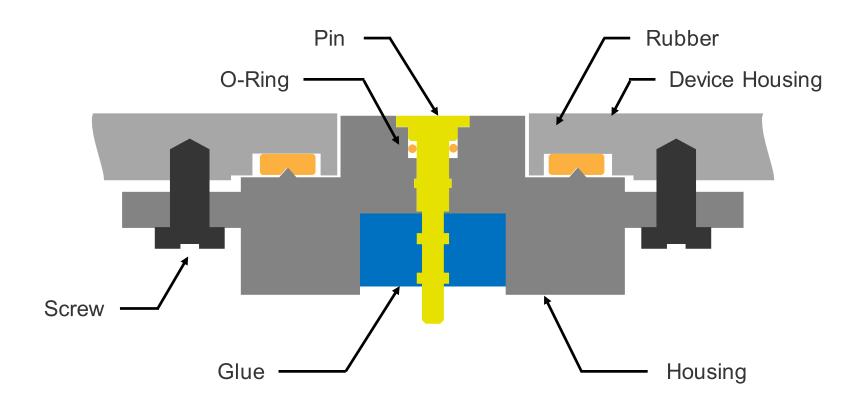
## Connector: 2 in 1 Laptop

High Frequency Magnetic Matting Desktop Docking





## **Connector:** Waterproof



## **Connector:** Waterproof

#### Sealing

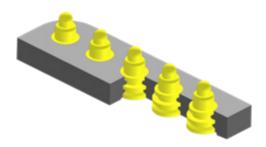


Pitch: Small

Waterproof: IPx7 at best

Production Complexity: Low

#### **Insert-Molding**

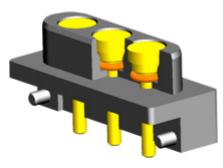


Pitch: Small

Waterproof: IPx7 at best

Production Complexity: Low

#### O-Ring

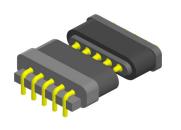


Pitch: Large

Waterproof: IPx8 at best

Production Complexity: High

## **Connector:** Customized



#### **Magnetic Modules**

Easy attachable and detachable connectors used for different applications





#### **Rugged Modules**

Able to achieve IP67 rating and to operate under extreme environments



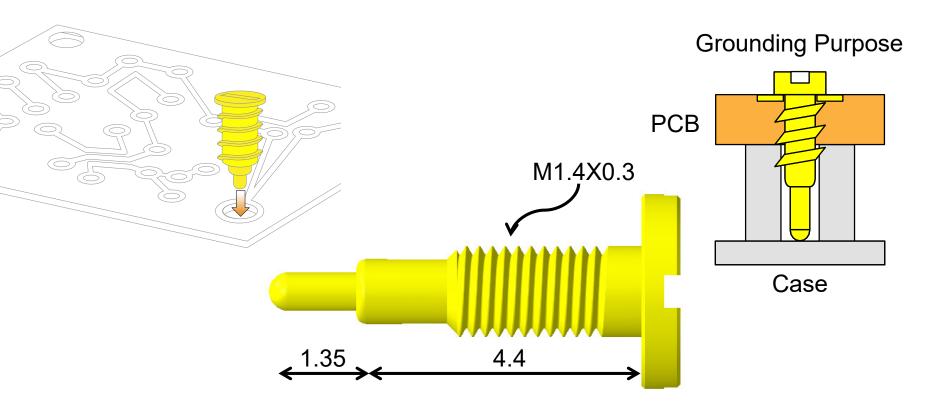


#### **Shielded Modules**

Shielded design for high speed signal transmission

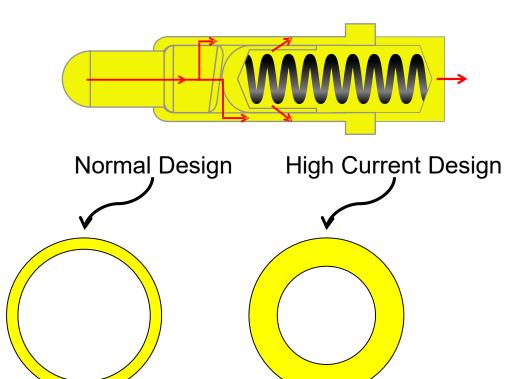


# Connector: Pogo Screw Pin



Diameter	Current	Durability
3 mm	1A	10,000 compressions
Spring force	Contact resistance	
120g ± 20g	200 M Ohm, to customize for grounding pin purpose	

## Connector: High Current Pogo

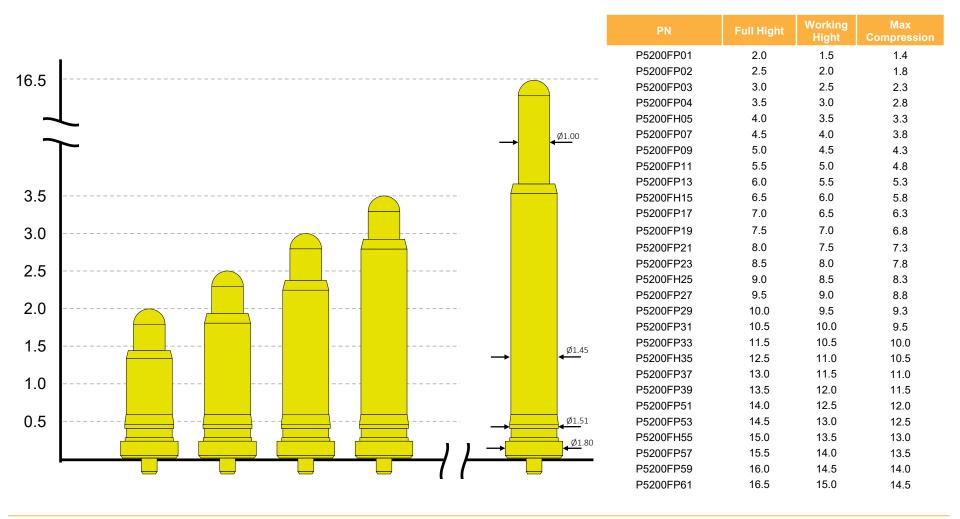




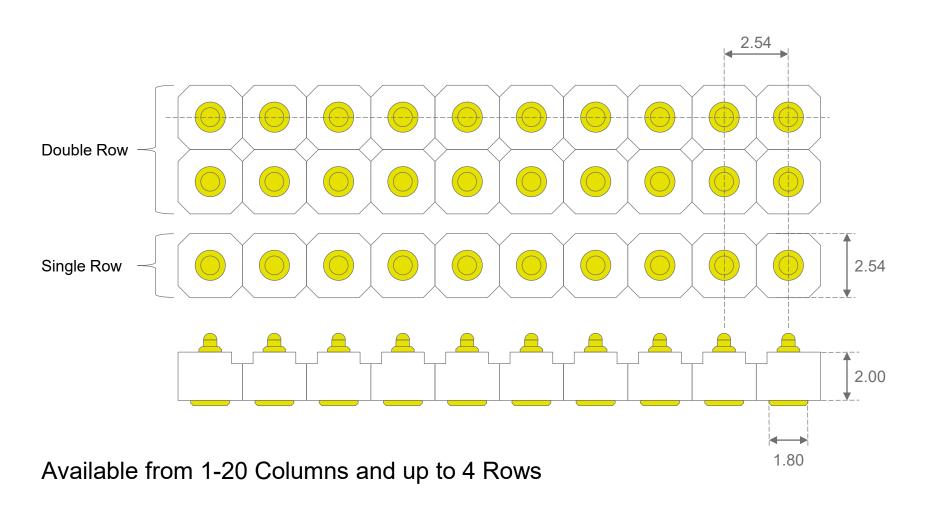
Application:
Any kind of high current transfer request

Diameter	Current	Durability
2.4 mm	13A 10,000 compressions	
Spring force	Contact resistance	
120g ± 20g	30 mΩ	

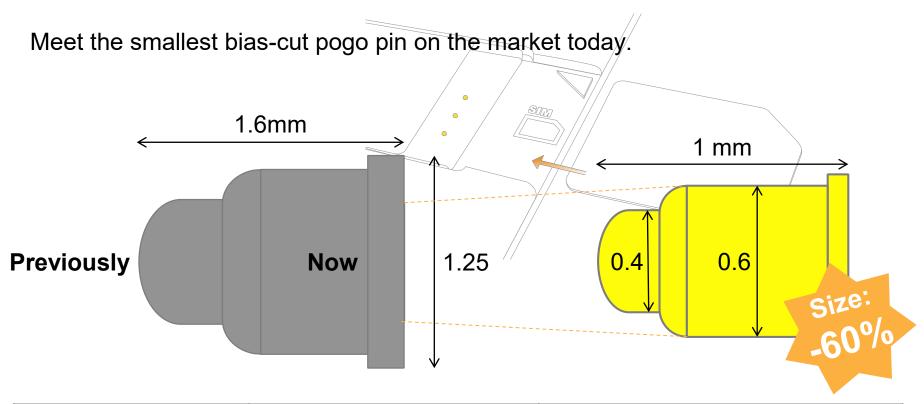
# Connector: 2.54mm Pitch Standard Connector Single Pitch



# Connector: 2.54mm Pitch Standard Housing

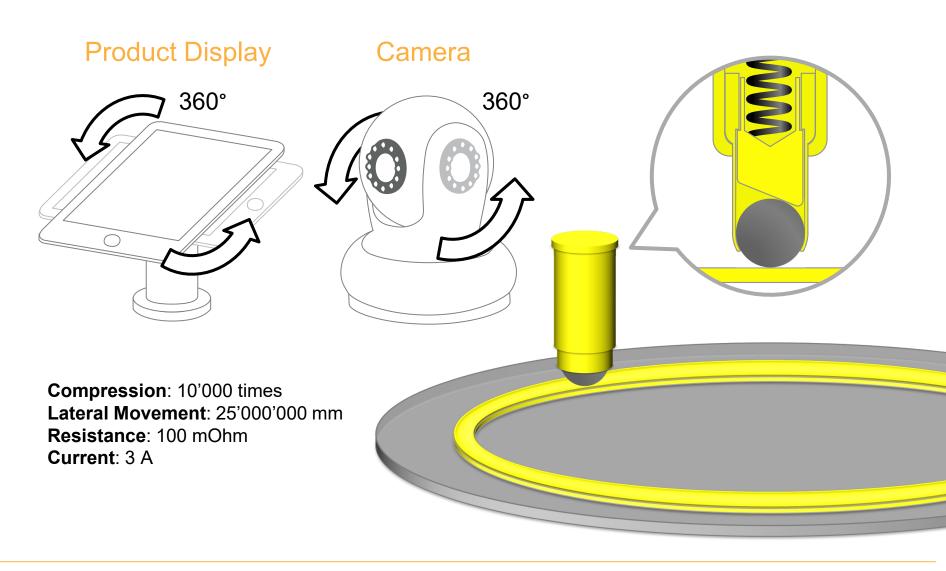


## **Connector:** Ultra Short Pin

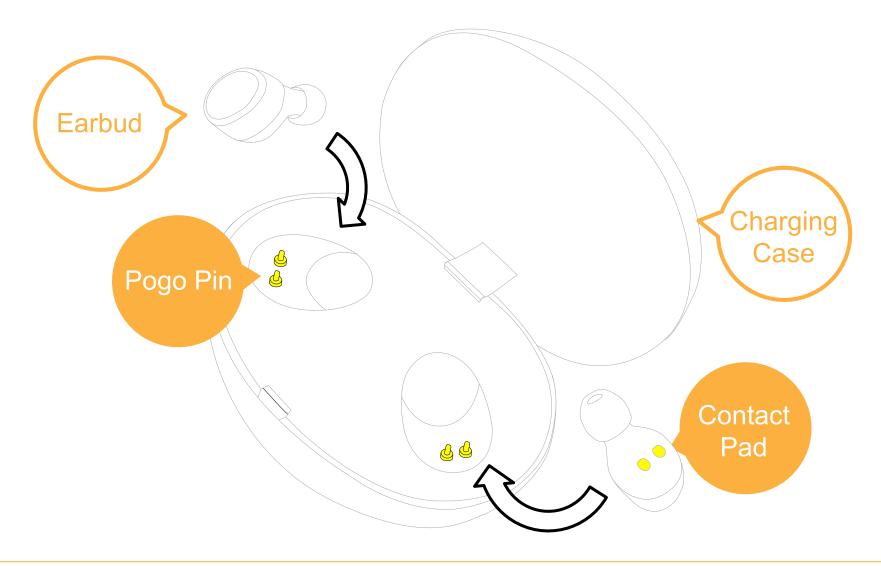


Diameter	Current	Durability
0.6 mm	1A	600 compressions
Spring force	Contact resistance	
145g ± 20g	100 mOhm, to customize for grounding pin purpose	

## **Connector:** Lateral Movement



## **Connector:** Wireless Earbuds



# **Connector:** Computer



# **Product Line:** New Energy



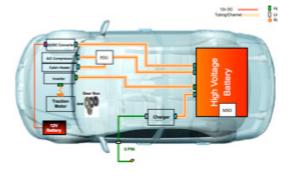
**EV** Charging



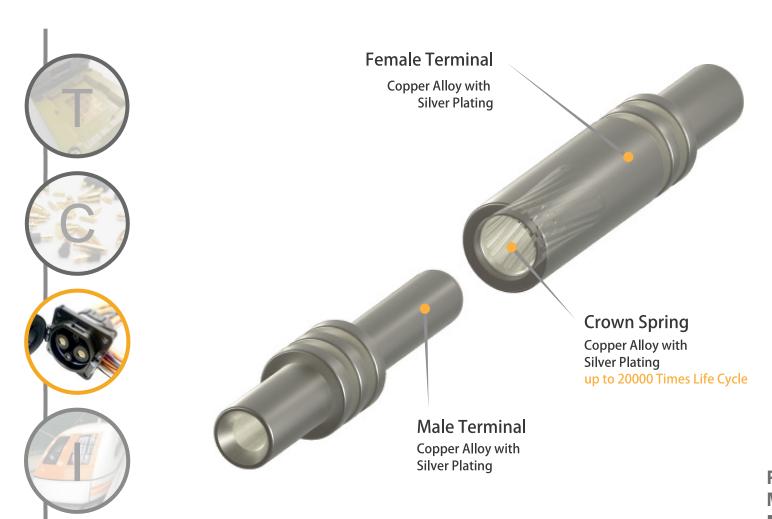
**Scooter Battery System** 



**EV Inner Ports** 



## **Product Line:** Performance



Patent No: MP1703244 MU1703245

# **High Current:** Applications



### **Charging module**

EV car charging solutions EV moped battery solutions





### Signal connector

Single plug connector Multiple plug connector Push-pull connector



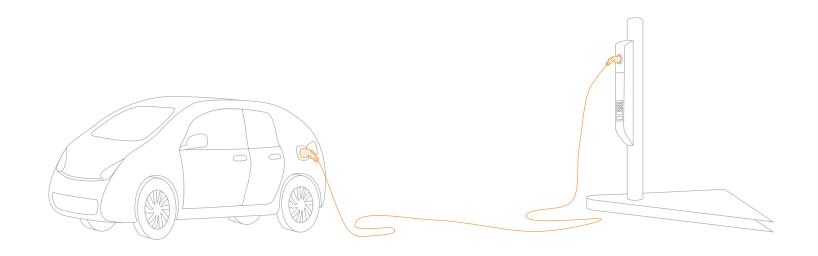


### **High voltage connector**

Single plug connector Multiple plug connector Push-pull connector



# High Current: EV Car Charging

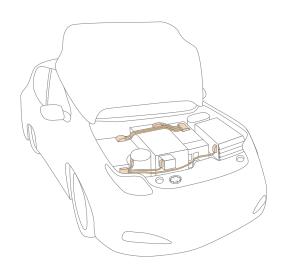


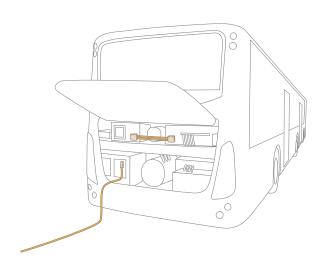




AC/DC Charging Socket

## **High Current:** EV Car Connections







High Voltage
Power Lock Connector



Signal Connector

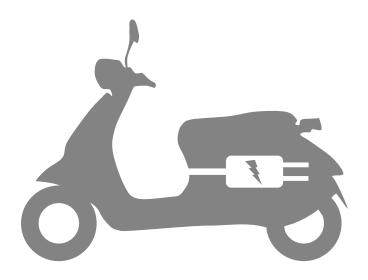


Push-Pull Connector



High Voltage Power Lock Module

## High Current: EV Scooter Solutions





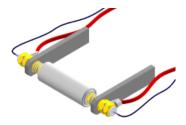
**Battery Module** 



Signal Connector

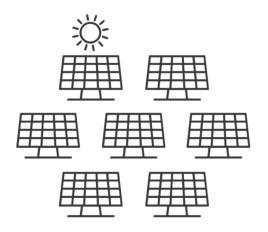


Battery Charging Solution



Battery Testing Solution

# High Current: Solar Panels and Robotics





**Battery Module** 



High Voltage
Power Lock Connector

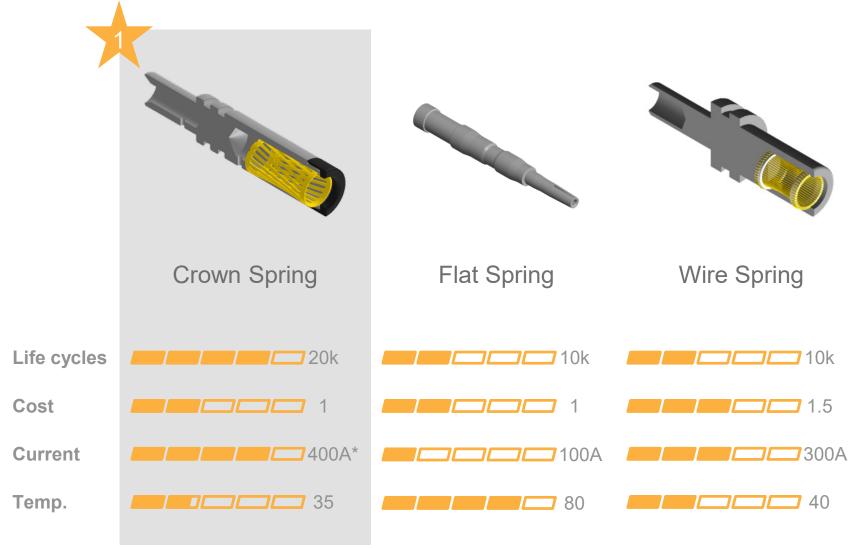


Current Diversion
Connector



High Voltage Power Lock Module

## High Current: Comparison



# **High Current:** Comparison

Structure		cturing cess Contact	Manufacture ability	Durability	LLCR	Current Capacity	Cost
Flat			_				_
Spring	Lathe	Lathe	Good	Poor	Poor	Poor	Good
Crown Spring	Lathe	Stamp	Good	Good	Good	Good	Good
Wire Spring	Lathe	Wire Spring	Poor	Excellent		Poor	
Spring Sets	Lathe	Spring	Poor	Poor	Poor	Poor	Poor

# **High Current:** Applications







	Crownspring	Socket	Plug		
Material	BeCu	Cu Alloy	y or Ag		
Process	Stamping	Turning b	by Lathe		
Plating	Gold Plating (Ag, Au, Ni)				
Interface	Tail with Screw or Crimping tail or others				
Head			Insulator Cap		
Remark	Tail with	n Screw or Crimping tail or	others		

# **High Current:** Standard Dimensions



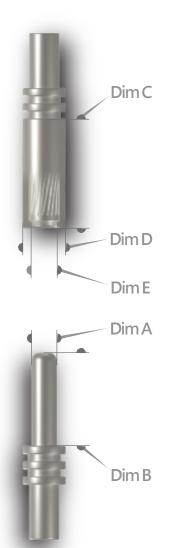
**China/ Europe Standard** 





**USA Standard** 

Current (Amp)	15	30	250	2	40	80		
Resistance (mOhm)	0.8	0.3	0.1	1	0.5	0.3		
Life Cycles	20,000	20,000	20,000	10,000	10,000	10,000		
	Dimensions							
Dim A (mm) (Width Plug)	3	6	12	1.5	2.8	3.6		
Dim B (mm) (Insertion Hight Plug)	14.5	28.5	30.5	12	24	21		
Dim C (mm) (Insertion Hight Socket)	32	32	42	12.9	18.7	14.6		
Dim D (mm) (Width Socket)	4.8	9.8	15.8	3.1	4.9	6.73		
Dim D (mm) (Inner Width Socket)	3.1	6.1	12.1	1.65	2.95	3.75		



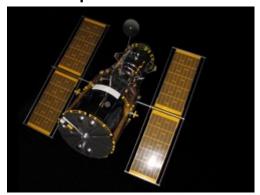
## **Product Line:** Industrial



Transportation



Aerospace



Military



# Automation and Mechanical Engineering

### **Inhouse Machinery Construction**

Full automation capability



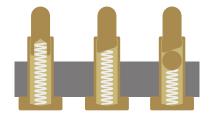
100% Inspection

**Pure Quality** 

**Clean-Room Production Line** 

# **Product Line:** Capacity

Pogo Pin Connectors



60 Mio pins / month

**Testing Probes** 



2 Mio pins / month



# **Quality Management**

## **Quality System**

ISO 9001: 2015

**Quality Management Systems** 

ISO 14001: 2015

**Environmental Management System** 

IATF 16949: 2016

Automotive Quality Management System

QC 080000

**Hazardous Substance Process Management** 

# **Quality Assurance**



# **Verification Ability**

## **Testing Items**

### **Environmental**

Waterproof
Humidity Test
Salt Spray
Thermal Impact
Resist. to Solder Heat
Vibration

### **Electrical**

Contact Resistance Insulation HIPOT Rated Current

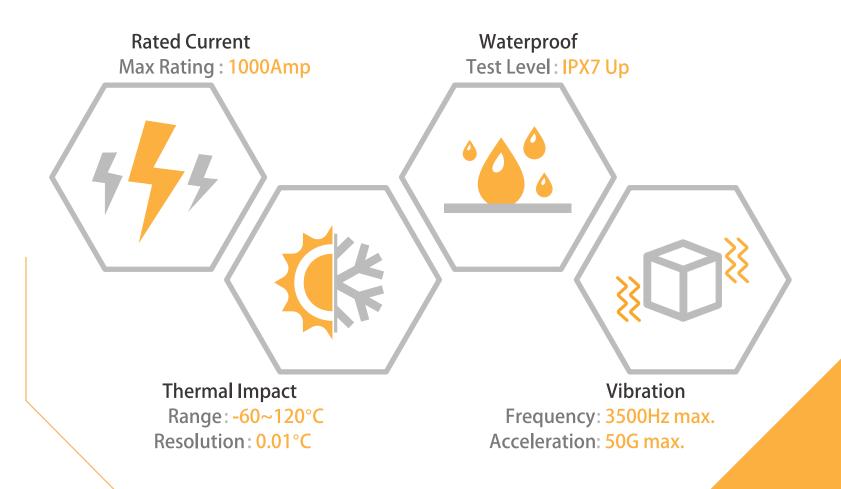
### Mechanical

Retention Force Life Cycle Vibration Mechanical Shock

### Other

Drop Soldering Side Force Solderability

# **Testing Equipment**



### Certificate



ISO 9001

ISO 14001

ISO 14064

IATF 16949

IECQ QC080000













